

Docket No.: MAS-FIN-403

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : BERND GOLLER ET AL.

Filed : CONCURRENTLY HEREWITH

Title : UNIVERSAL SEMICONDUCTOR HOUSING WITH
PRECROSSLINKED PLASTIC EMBEDDING COMPOUNDS,
AND METHOD OF PRODUCING THE SEMICONDUCTOR
HOUSING

INFORMATION DISCLOSURE STATEMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

In accordance with 37 C.F.R. 1.98 copies of the following patents and/or publications are submitted herewith:

U.S. Patent No. 5,306,670 (Mowatt et al.), dated April 26, 1994;

U.S. Patent No. 5,923,958 (Chou), dated July 13, 1999;

U.S. Patent No. 5,990,546 (Igarashi et al.), dated November 23, 1999;

U.S. Patent No. 5,032,543 (Black et al.), dated July 16, 1991;

U.S. Patent No. 5,879,964 (Paik et al.), dated March 9, 1999;

U.S. Patent No. 5,972,735 (Dominic), dated October 26, 1999;

U.S. Patent No. 5,144,747 (Eichelberger), dated September 8, 1992;

U.S. Patent No. 6,239,482 B1 (Fillion et al.), dated May 29, 2001;

U.S. Patent Application Publication No. 2003/0040142 A1 (Lin et al.), dated February 27, 2003;

Patent Abstracts of Japan 2001093940 A (Yuji), dated April 6, 2001;

European Patent Specification EP 0 611 129 B1 (Fillion et al.), dated August 17, 1994;

PCT WO 88/03704 (Bolster et al.), dated May 19, 1988;

PCT WO 97/22993 (Oggioni), dated June 26, 1997;

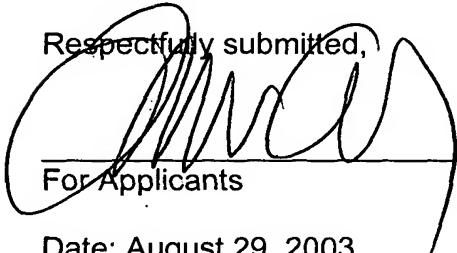
PCT WO 92/17901 (Eichelberger), dated October 15, 1992;

PCT WO 96/04611 (Druschke et al.), dated February 15, 1996, and corresponding German Published Non-Prosecuted Patent Application DE 44 27 309 A1 (Druschke et al.), dated February 15, 1996;

Okuno, A. et al.: "High Reliability, High Density, Low Cost Packaging Systems for Matrix Systems for Matrix BGA and CSP by Vacuum Printing Encapsulation Systems (VPES)", IEEE Transactions on Advanced Packaging, Vol. 22, No. 3, August 1999, pp. 391-397.

If no translation of pertinent portions of any foreign language patents or publications mentioned above is included with the aforementioned copies of those applications, patents and/or publications, it is because no existing translation is readily available to the applicant.

Respectfully submitted,


For Applicants

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Date: August 29, 2003

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/nt/kf

FORM PTO-1449 (SUBSTITUTE)		Attorney Docket No.: MAS-FIN-403
U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE		Appl. No.:
INFORMATION DISCLOSURE STATEMENT BY APPLICANT (37 CFR 1.98(b))		Applicant: BERND GOLLER ET AL.
		Filing Date: August 29, 2003
		Group Art Unit:

EXAMINER INITIALS	PATENT NO.	DATE	PATENTEE	CLASS	SUB CLASS	FILING DATE
A	5,306,670	4/26/94	Mowatt et al.			
B	5,923,958	7/13/99	Chou			
C	5,990,546	11/23/99	Igarashi et al.			
D	5,032,543	7/16/91	Black et al.			
E	5,879,964	3/9/99	Paik et al.			
F	5,972,735	10/26/99	Dominic			
G	5,144,747	9/8/92	Eichelberger			
H	6,239,482 B1	5/29/01	Fillion et al.			
I	2003/0040142 A1	2/27/03	Lin et al.			

FOREIGN PATENT DOCUMENT

	DOCUMENT NO.	DATE	COUNTRY	CLASS	SUB CLASS	TRANSL. YES NO
J	44 27 309 A1	2/15/96	Germany			
K	2001093940 A	4/6/01	Japan			
L	0 611 129 B1	8/17/94	Europe			
M	88/03704	5/19/88	WIPO			
N	97/22993	6/26/97	WIPO			

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, etc.)

EXAMINER	DATE CONSIDERED

FORM PTO-1449 (SUBSTITUTE)		Attorney Docket No.: MAS-FIN-403					
U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE		Appl. No.:					
INFORMATION DISCLOSURE STATEMENT BY APPLICANT (37 CFR 1.98(b))		Applicant: BERND GOLLER ET AL.					
		Filing Date: August 29, 2003 Group Art Unit:					

EXAMINER INITIALS		PATENT NO.	DATE	PATENTEE	CLASS	SUB CLASS	FILING DATE
	A						
	B						
	C						
	D						
	E						
	F						
	G						
	H						
	I						

FOREIGN PATENT DOCUMENT

		DOCUMENT NO.	DATE	COUNTRY	CLASS	SUB CLASS	TRANSL. YES NO
	J	92/17901	10/15/92	WIPO			
	K	96/04611	2/15/96	WIPO			
	L						
	M						
	N						

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, etc.)

		Okuno, A. et al.: "High Reliability, High Density, Low Cost Packaging Systems for Matrix Systems for Matrix BGA and CSP by Vacuum Printing Encapsulation Systems (VPES)", IEEE Transactions on Advanced Packaging, Vol. 22, No. 3, August 1999, pp. 391-397
EXAMINER		DATE CONSIDERED